Amendments to the Specification:

Please amend paragraph [0017] and [0018] as shown below.

[0017] In accordance with the present invention, PWB 201 and electronic components 202, 204 are placed inside outer shell 211. Outer shell 211 preferably comprise thin, lightweight and stiff composite planar sheets made of, e.g., carbon fiber. The planar sheets are spaced from each other via at least one of spacer 230 and connector 220. To provide the desired rigidity to PWB 201 and mounted electronic components 202, 204, the void between outer shell 211 and PWB 201 and electronic components 202, 204 is preferably filled with lightweight filter 215. Lightweight filler 215can be, for example, expandable foam, which is injected into outer shell 211 through squirt holes 212 (only two are shown for simplification) of outer shell 211. Preferably, filler 215 is dynamically tuned to optimize at least (1) dynamic response of circuit card assembly 200, (2) moisture control, and (3) ~~(2)~~ reworkability of circuit card assembly 200. The term "dynamically tuned" is intended to mean that the dynamic characteristics (natural frequency and amplitude at resonance) of circuit card assembly 200 are adjusted (tuned) to provide the least sensitivity to dynamic environments imposed on the assembly.

[0018] To compensate for heat dissipating components, the present invention preferably further provides thermal fillers 205 at voids between shell 211 and electronic components 204 that generate heat when in use. Thermal filler 205 can be, for example, silver-filled silicone or epoxy, both of which have good thermal properties. By using thermal fillers, the heat generated by electronic elements 204 can be more easily transferred from a given component to outer shell 211 and thus outside of CCA 200. In accordance with the present invention, the material of

outer shell 211 is selected to provide a good medium for heat transfer, in addition to providing lightweight stiffness. It is also noted that outer shell 211 can also provide EMI shielding. Thermal filler 205 ~~25~~ is preferably injected via squirt hole 204, which is positioned adjacent a heat-generating component.